

ORS

APPLICATION NOTES

In Situ Monitoring for VCSEL

Advantages of live, *in situ* monitoring for manufacturing of VCSEL

- ∞ Direct comparison possible between *in situ* growth-rate measurement and *ex situ* centre stop band (CSB) measurement;
- ∞ Automatic, real-time analysis of the growth rate allows for control of the VCSEL process;
- ∞ Guaranteed VCSEL yield improvement ensured by targeting
 - +/- 5nm CSB
 - +/- 3nm CSB

Live, *in situ* growth-rate monitoring now provides a guaranteed method of increased product yield for VCSEL, with direct correlation possible to *ex situ* characterisation methods.

By controlling the growth rate of the initial layers of the n-type DBR, it is possible to ensure that the centre stop band specification is hit and maintained, increasing process yield. The figures below show *ex situ* reflectance wafer map data and *in situ* reflectance data for an in-spec wafer.

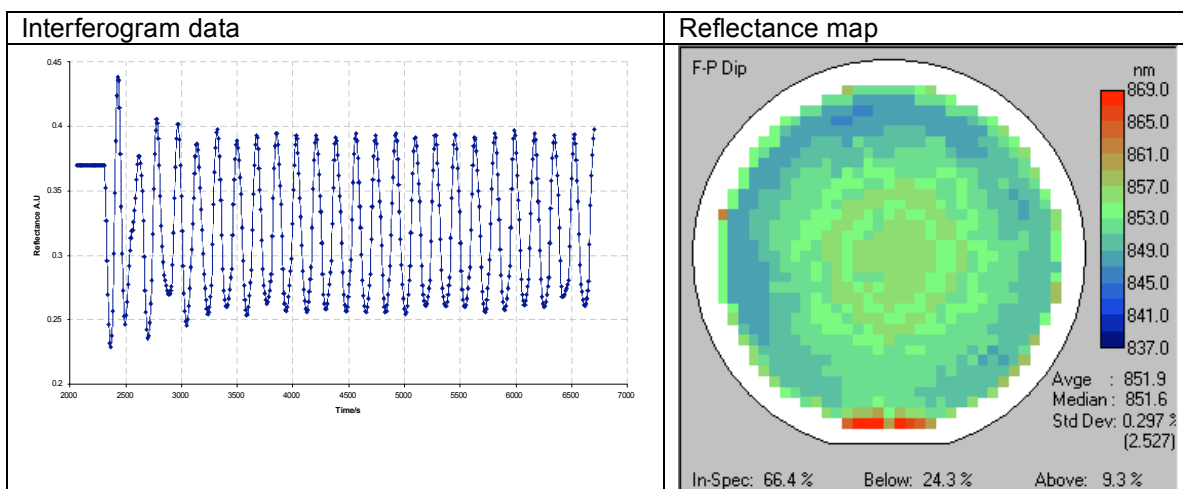


Figure 1: In situ growth rate measurement and ex situ PL measurement

The data for the CSB measurement from the PL is then compared to the *in situ* growth-rate measurement with a high degree of reliability.

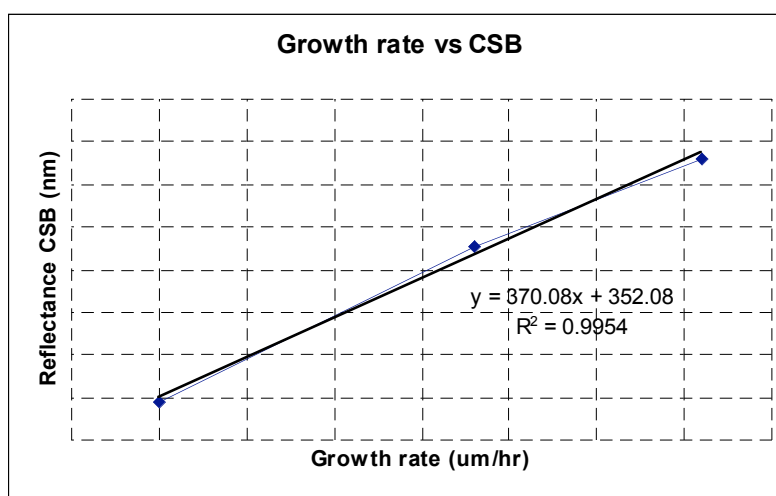


Figure 2: Comparison of ex situ CSB measurement to in situ growth-rate measurement